

# GSDE1□D2F Series

## Fast Recovery Diode

### Product Description

Reverse Voltage 50V to 600V.  
Forward Current 1.0A



### Features

- Low Reverse Recovery Time
- RoHS Compliant and Halogen Free

### Mechanical Data

- SOD-123FL Package
- Polarity: Color Band denotes Cathode End

### Package and Pin Assignment

SOD-123FL		Equivalent Circuit
		
Pin	Description	
1	Anode	
2	Cathode	

### Ordering and Marking Information

Ordering Information			
Part Number	V <sub>RRM</sub>	Marking Code	Quantity/Reel
GSDE1AD2F	50	E1A	3000 PCS
GSDE1BD2F	100	E1B	3000 PCS
GSDE1DD2F	200	E1D	3000 PCS
GSDE1GD2F	400	E1G	3000 PCS
GSDE1JD2F	600	E1J	3000 PCS

<b>GSDE1 □ D2 F</b>		
<b>- Product Code:</b> GSDE1	<b>- Voltage Code:</b> □ is A, B, D. G or J stands for Maximum repetitive peak reverse voltage.	<b>- Package Code:</b> D2 for SOD-123FL Package
<b>- Green Level:</b> F for RoHS Compliant and Halogen Free		


### Marking Information

**E1** 

- **Product Code:**

E1

- **Voltage Code:**

 is A, B, D, G or J stands for Maximum repetitive peak reverse voltage.

### Electrical Characteristics (Ratings at 25°C Ambient Temperature Unless Otherwise Specified.)

Symbol	Conditions	E1A	E1B	E1D	E1G	E1J	Unit
$V_{RRM}$	Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	V
$V_{RMS}$	Maximum RMS Voltage	35	70	140	280	420	V
$V_{DC}$	Maximum DC Blocking Voltage	50	100	200	400	600	V
$I_{F(AV)}$	Maximum Average Forward Rectified Current	1					A
$I_{FSM}$	Peak Forward Surge Current (8.3ms Single Half Sinewave)	30					A
$V_F$	Maximum Forward Voltage at 1.0A	0.95		1.25		1.7	V
$I_R$	Maximum Reverse Leakage Current at rated $V_R$	$T_A = 25^\circ\text{C}$	5				$\mu\text{A}$
		$T_A = 100^\circ\text{C}$	100				$\mu\text{A}$
$t_{rr}$	Maximum reverse recovery time <sup>(1)</sup>	35					ns
$C_J$	Typical Junction Capacitance <sup>(2)</sup>	10					pF
$R_{\theta JA}$	Typical Thermal Resistance <sup>(3)</sup>	85					$^\circ\text{C}/\text{W}$
$T_J$	Operating Junction Temperature Range	-55 to +150					$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to +150					$^\circ\text{C}$

**NOTES:**

1. Measured with  $I_F=0.5\text{A}$ ,  $I_R=1\text{A}$ ,  $I_{rr}=0.25\text{A}$ .
2. Measured at 1MHz and applied reverse voltage of  $4.0V_{DC}$
3. Mounted with  $0.2 \times 0.2$ " ( $5.0 \times 5.0\text{mm}$ ) Copper Pad Areas

## Typical Characteristics (Ratings at 25°C Ambient Temperature Unless Otherwise Specified.)

FIG. 1- FORWARD CURRENT DERATING CURVE

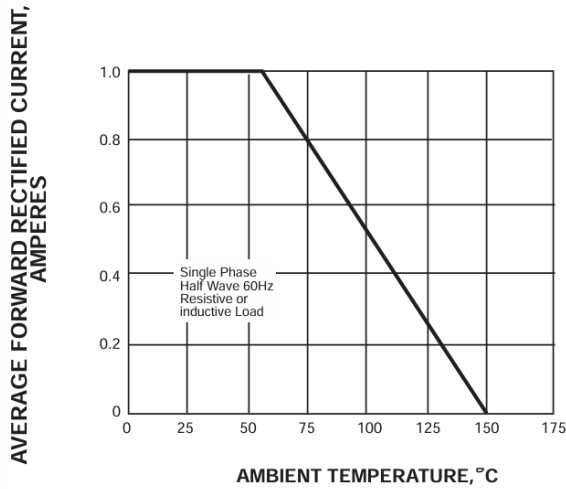


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

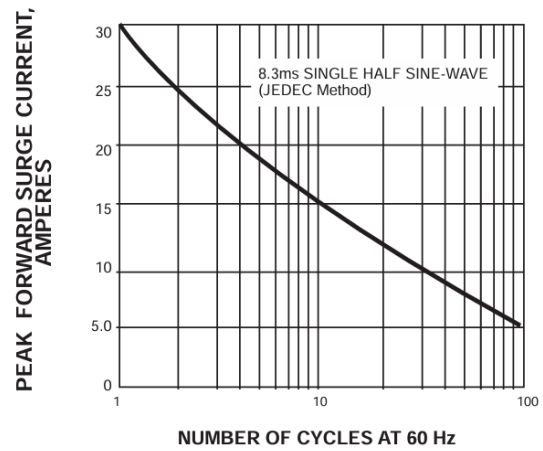


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

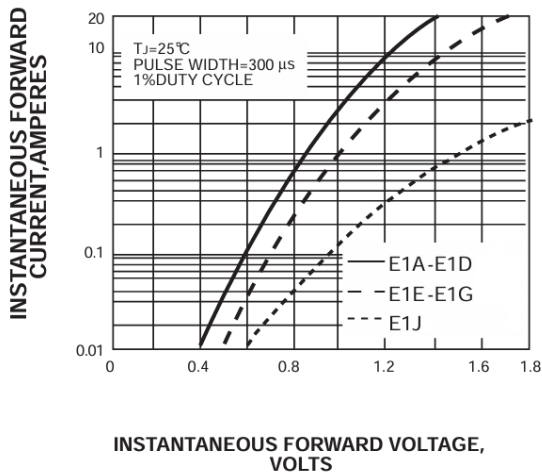


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

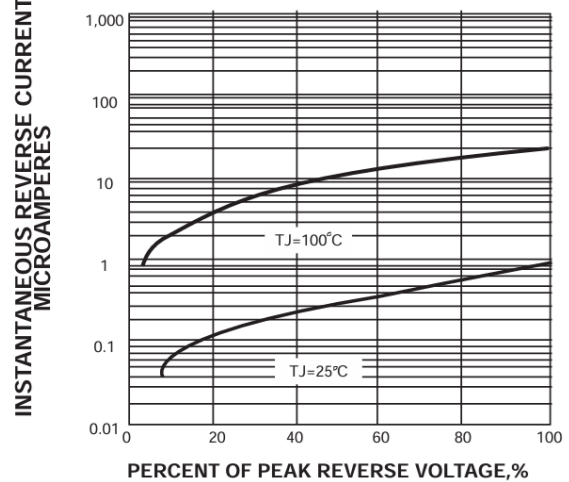


FIG. 5-TYPICAL JUNCTION CAPACITANCE

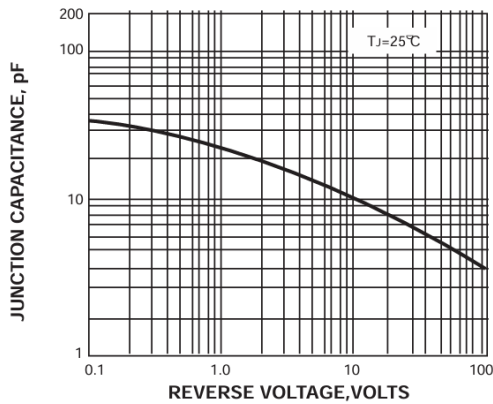
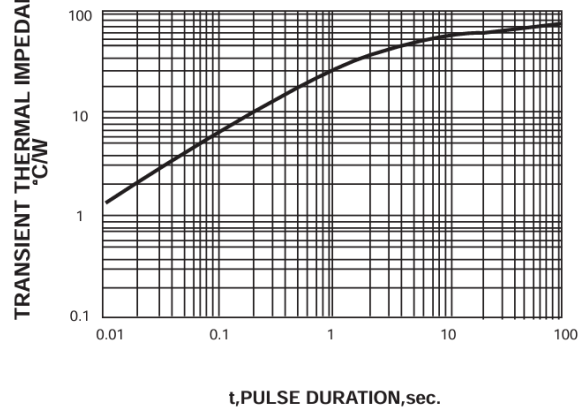
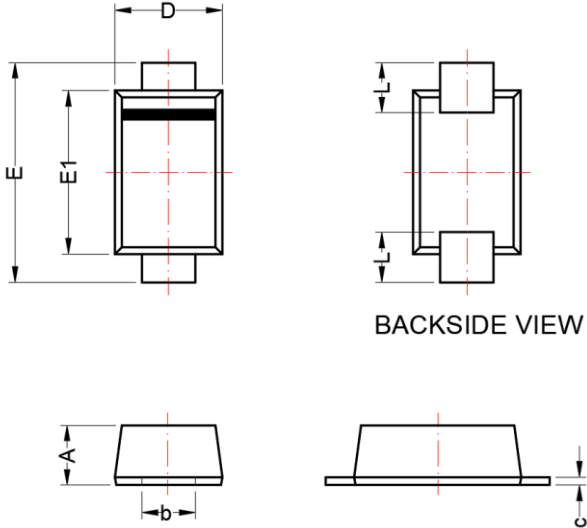


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE

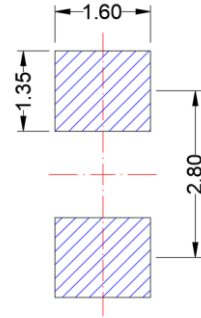


# SOD-123FL

## Package Dimension



## Recommended Land Pattern



(Unit: mm)

Dimensions				
Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	0.80	1.10	0.031	0.043
b	0.50	1.20	0.020	0.047
D	1.50	1.90	0.059	0.075
E	3.30	3.80	0.130	0.150
E1	2.45	2.75	0.096	0.108
c	0.05	0.20	0.002	0.008
L	0.70	0.90	0.028	0.035





### NOTE:



1. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.
2. Terminals are partially uncovered on the bottom of package body

## NOTICE

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